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ABSTRACT

A method of manufacturing the solid electrolytic capacitors that can be directly connected to semiconductor components and have a faster response to a high frequency as well as a larger capacitance includes: a dielectric forming stage where a valve metal sheet (2) is made porous and dielectric coating (7) is provided on the porous face (3); an element forming stage where solid electrolytic layer (8) and collector layer (10) are formed on the dielectric coating (7); and a terminal forming stage where connecting terminal (16) to an external electrode is formed. The element forming stage includes the steps of: forming solid electrolytic layer (8); forming through-hole electrode (9) in through-hole (5) that is prepared on valve metal sheet (2); and forming collector (10) on solid electrolytic layer (8).